

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6123466

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CORRECTIVE BY NULLIFICATION TO CORRECT THE RECEIVING PARTY INCORRECTLY RECORDED previously recorded on Reel 036594 Frame 0761. Assignor(s) hereby confirms the ASSIGNMENT.
RESUBMIT DOCUMENT ID:	506040754

CONVEYING PARTY DATA

Name	Execution Date
COLLIN JENNINGS COOLIDGE	10/02/2018
SHANSHAN XU	08/31/2018
RONGGUI YANG	10/08/2018
CHING-YI LIN	09/10/2018
YUNG-CHENG LEE	02/08/2019
RYAN JOHN LEWIS	06/05/2018
LI-ANNE LIEW	05/23/2018

RECEIVING PARTY DATA

Name:	THE REGENTS OF THE UNIVERSITY OF COLORADO, A BODY CORPORATE
Street Address:	1800 GRANT STREET
Internal Address:	8TH FLOOR
City:	DENVER
State/Country:	COLORADO
Postal Code:	80203

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14857567

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3853216179
 Email: audri@sandersiplaw.com
 Correspondent Name: SANDERS IP
 Address Line 1: 240 N. EAST PROMONTORY
 Address Line 2: SUITE 200

Address Line 4:	FARMINGTON, UTAH 84025
ATTORNEY DOCKET NUMBER:	K2212.10002US02
NAME OF SUBMITTER:	JASON A. SANDERS
SIGNATURE:	/Jason A. Sanders/
DATE SIGNED:	05/27/2020
Total Attachments: 8 source=K2212.10002US02-CorrectedAssignmentSigned#page1.tif source=K2212.10002US02-CorrectedAssignmentSigned#page2.tif source=K2212.10002US02-CorrectedAssignmentSigned#page3.tif source=K2212.10002US02-CorrectedAssignmentSigned#page4.tif source=K2212.10002US02-CorrectedAssignmentSigned#page5.tif source=K2212.10002US02-CorrectedAssignmentSigned#page6.tif source=K2212.10002US02-CorrectedAssignmentSigned#page7.tif source=K2212.10002US02-Original Cover Sheet#page1.tif	

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	MICROPILLAR-ENABLED THERMAL GROUND PLANE
Docket Number	K2212.10002US02

As the below named inventor, I hereby declare that:
 This declaration is directed to: The attached application, or United States application or PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.
 I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
 I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

The Regents of the University of Colorado, a body corporate
 WHEREAS, Kelvin Thermal Technologies, Inc. (hereinafter referred to as "ASSIGNEE") having a place of business at: 5425 Illini Way, Boulder, Colorado, 80303; desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application; 1800 Grant Street, 8th Floor, Denver, Colorado 80203

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I hereby assign to the ASSIGNEE, the entire right, title and interest in said invention and in the above-identified United States patent application and in all divisions, continuations and continuations-in-part of said application, and reissues, extensions and renewals of Letters Patent granted thereon, and in all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and in all Letters Patents issuing on any such patent applications in the United States and foreign countries;


I hereby assign to the ASSIGNEE the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any other relevant treaties;

I hereby authorize and request the United States Patent & Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of the ASSIGNEE, its successors, assigns, and legal representatives, to the full end of the term for which said Letters Patent may be granted; and

Further, I agree that, without further consideration, I will communicate to the ASSIGNEE any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitute, renewal and reissue applications, execute all necessary assignment papers to cause said Letters Patent to be issued to the ASSIGNEE, make all rightful oaths, and, perform all lawful acts to aid the ASSIGNEE, its successors and assigns, to obtain and enforce Letters Patent for said invention in the United States and foreign countries.

LEGAL NAME OF INVENTOR *CJC 10/2/18*

Inventor: Collin Jennings Coolidge Date: 9/9/19

Signature: 

MASCHOFF BRENNAN, PLLC
 1389 Center Drive, SUITE 300
 PARK CITY, UTAH 84098, USA

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	MICROPILLAR-ENABLED THERMAL GROUND PLANE	
Docket Number	K2212.10002US02	
As the below named inventor, I hereby declare that:		
This declaration is directed to:	<input checked="" type="checkbox"/>	The attached application, or
	<input type="checkbox"/>	United States application or PCT international application number _____ filed on _____.
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
The Regents of the University of Colorado, a body corporate		
WHEREAS, Kelvin Thermal Technologies, Inc. (hereinafter referred to as "ASSIGNEE") having a place of business at: 5429 Illini Way, Boulder, Colorado, 80303, desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application; 1800 Grant Street, 8th Floor, Denver, Colorado 80203		
NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I hereby assign to the ASSIGNEE, the entire right, title and interest in said invention and in the above-identified United States patent application and in all divisions, continuations and continuations-in-part of said application, and reissues, extensions and renewals of Letters Patent granted thereon, and in all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and in all Letters Patents issuing on any such patent applications in the United States and foreign countries;		
I hereby assign to the ASSIGNEE the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any other relevant treaties;		
I hereby authorize and request the United States Patent & Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of the ASSIGNEE, its successors, assigns, and legal representatives, to the full end of the term for which said Letters Patent may be granted; and		
Further, I agree that, without further consideration, I will communicate to the ASSIGNEE any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitute, renewal and reissue applications, execute all necessary assignment papers to cause said Letters Patent to be issued to the ASSIGNEE, make all rightful oaths, and, perform all lawful acts to aid the ASSIGNEE, its successors and assigns, to obtain and enforce Letters Patent for said invention in the United States and foreign countries.		
LEGAL NAME OF INVENTOR		
Inventor:	<u>Shanshan Xu</u>	Date: <u>9/9/2015</u>
Signature:	<u>Shanshan Xu SX 8/31/2018</u>	

MASCHOFF BRENNAN, PLLC
1389 Center Drive, SUITE 300
PARK CITY, UTAH 84098, USA

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	VACUUM-ENHANCED HEAT SPREADER
Docket Number	K2212.10001US02

As the below named inventor, I hereby declare that:

This declaration is directed to: The attached application, or
 United States application or PCT international application number _____ filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

The Regents of the University of Colorado, a body corporate

WHEREAS, ~~Kevin Thermal Technologies, Inc~~ (hereinafter referred to as "ASSIGNEE") having a place of business at: ~~5429 Illini Way, Boulder, Colorado, 80303~~, desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application; 1800 Grant Street, 8th Floor, Denver, Colorado 80203

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I hereby assign to the ASSIGNEE, the entire right, title and interest in said invention and in the above-identified United States patent application and in all divisions, continuations and continuations-in-part of said application, and reissues, extensions and renewals of Letters Patent granted thereon, and in all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and in all Letters Patents issuing on any such patent applications in the United States and foreign countries;

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LEGAL NAME OF INVENTOR

Inventor: Ronggui Yang

Date: 9-9-2015

Signature: 

MASCHOFF BRENNAN, PLLC
 1389 Center Drive, SUITE 300
 PARK CITY, UTAH 84098, USA

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	MICROPILLAR-ENABLED THERMAL GROUND PLANE
Docket Number	K2212.10002US02

As the below named inventor, I hereby declare that:

This declaration is directed to: The attached application, or
 United States application or PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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The Regents of the University of Colorado, a body corporate
 WHEREAS, Kelvin Thermal Technologies, Inc (hereinafter referred to as "ASSIGNEE") having a place of business at: 5429 Illini Way, Boulder, Colorado, 80303, desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application; 1800 Grant Street, 8th Floor, Denver, Colorado 80203

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LEGAL NAME OF INVENTOR

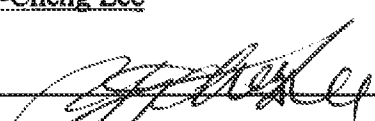
Inventor: Ching-Yi Lin

Date: 9/9/2015

Signature: *Ching-Yi Lin*

MASCHOFF BRENNAN, PLLC
 1389 Center Drive, SUITE 300
 PARK CITY, UTAH 84098, USA

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Title of Invention	MICROPILLAR-ENABLED THERMAL GROUND PLANE	
Docket Number	K2212.10002US02	
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This declaration is directed to:	<input checked="" type="checkbox"/>	The attached application, or
	<input type="checkbox"/>	United States application or PCT international application number _____ filed on _____.
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
The Regents of the University of Colorado, a body corporate <i>YCL, 2/8/2019</i>		
WHEREAS, Kelvin Thermal Technologies, Inc (hereinafter referred to as "ASSIGNEE") having a place of business at: 5429 Hillin Way, Boulder, Colorado, 80303 , desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application; <u>1800 Grant Street, 8th Floor, Denver, Colorado 80203</u>		
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LEGAL NAME OF INVENTOR		
Inventor:	<u>Yung-Cheng Lee</u>	Date: <u>9/9/2015</u>
Signature:		

MASCHOFF BRENNAN, PLLC
1389 Center Drive, SUITE 300
PARK CITY, UTAH 84098, USA

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	MICROPILLAR-ENABLED THERMAL GROUND PLANE
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RL 5 June 2018

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LEGAL NAME OF INVENTOR

Inventor: Ryan John Lewis


Date: 9/8/2015

Signature: _____

Ryan Lewis

MASCHOFF BRENNAN, PLLC
1389 Center Drive, SUITE 300
PARK CITY, UTAH 84098, USA

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	MICROPILLAR-ENABLED THERMAL GROUND PLANE	
Docket Number	K2212.10002US02	
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The above-identified application was made or authorized to be made by me.		
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LEGAL NAME OF INVENTOR		
Inventor:	<u>Li-Anne Liew</u>	Date: <u>9/9/15</u>
Signature:	<u>LL 5/23/18</u> 	

MASCHOFF BRENNAN, PLLC
 1389 Center Drive, SUITE 300
 PARK CITY, UTAH 84098, USA

PATENT
REEL: 052757 FRAME: 0571

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3531527

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHING-YI LIN	09/09/2015
RONGGUI YANG	09/09/2015
SHANSHAN XU	09/09/2015
LI-ANNE LIEW	09/09/2015
COLLIN JENNINGS COOLIDGE	09/09/2015
YUNG-CHENG LEE	09/09/2015
RYAN JOHN LEWIS	09/08/2015
RECEIVING PARTY DATA	
Name:	KELVIN THERMAL TECHNOLOGIES, INC.
Street Address:	5429 ILLINI WAY
City:	BOULDER
State/Country:	COLORADO
Postal Code:	80303
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14857567
CORRESPONDENCE DATA	
Fax Number:	(435)252-1361
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	435-252-1360
Email:	apayne@mabr.com
Correspondent Name:	MASCHOFF BRENNAN
Address Line 1:	1389 CENTER DRIVE, SUITE 300
Address Line 4:	PARK CITY, UTAH 84098
ATTORNEY DOCKET NUMBER:	K2212.10002US02
NAME OF SUBMITTER:	JASON A. SANDERS
SIGNATURE:	/Jason A. Sanders, Reg. No. 59984/
DATE SIGNED:	09/17/2015